



Product Change Notification / KSRA-06MRSR308

Date:

15-Apr-2021

Product Category:

Clock and Timing - Oscillators

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4610 Initial Notice: Qualification of a new lead frame with Full PPF die attach paddle (DAP) surface prep material for DSC11xx, DSC12xx and DSC81xx device families available in 6L VDFN (7x5x0.9mm) package at NSEB assembly site.

Affected CPNs:

[KSRA-06MRSR308_Affected_CPN_04152021.pdf](#)

[KSRA-06MRSR308_Affected_CPN_04152021.csv](#)

Notification Text:

PCN Status: Initial notification.

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of a new lead frame with Full PPF die attach paddle (DAP) surface prep material for DSC11xx, DSC12xx and DSC81xx device families available in 6L VDFN (7x5x0.9mm) package at NSEB assembly site..

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited (NSEB)	UTAC Thai Limited (NSEB)

Wire material	Au	Au
Die attach material	HR-5104 / 2200D	HR-5104 / 2200D
Molding compound material	G700LTD	G700LTD
Lead frame material	C194	C194
Lead Plating	NiPdAu	NiPdAu
Lead frame die attach paddle (DAP) surface prep material	Selective PPF	Full PPF
	See Pre and Post Change attachment for lead frame die attach paddle (DAP) surface prep material comparison	

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying a new lead frame with Full PPF die attach paddle (DAP) surface prep material.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:October 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	April 2021					-->	October 2021				
	1 4	1 5	1 6	1 7	1 8		4 0	4 1	4 2	4 3	4 4
Initial PCN Issue Date				X							
Qual Report Availability										X	
Final PCN Issue Date										X	

Method to Identify Change: Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:April 15, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_KSRA-06MRSR308_Pre and Post Change Summary.pdf](#)
[PCN_KSRA-06MRSR308_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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QUALIFICATION PLAN SUMMARY

PCN #: KSRA-06MRSR308

**Date:
March 18, 2021**

Qualification of a new lead frame with Full PPF die attach paddle (DAP) surface prep material for DSC11xx, DSC12xx and DSC81xx device families available in 6L VDFN (7x5x0.9mm) package at NSEB assembly site.

Purpose: Qualification of a new lead frame with Full PPF die attach paddle (DAP) surface prep material for DSC11xx, DSC12xx and DSC81xx device families available in 6L VDFN (7x5x0.9mm) package at NSEB assembly site.

CCB No.: 4610

<u>Misc.</u>	Assembly site	UTL (NSEB)
	BD Number	BDM-002880A
	MP Code (MPC)	3610Q5HPA003
	Part Number (CPN)	D50N-M3
	MSL information	MSL-1@260C
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	50 units
	Reliability Site	MTAI
<u>Lead-Frame</u>	Paddle size	COL
	Material	C194
	DAP Surface Prep	Full PPF
	Treatment	Yes
	Process	Etched
	Lead-lock	Yes
	Part Number	FR1684
	Lead Plating	NiPdAu
	Strip Size	70x250 mm
	Strip Density	320 units
<u>Bond Wire</u>	Material	Au
<u>Die Attach</u>	Part Number	TALA1 = HR-5104 (DAF), 59401 = 2200D
	Conductive	HR-5104 = Non conductive, 2200D = Conductive
<u>Die Coat</u>	Part Number	JCR6109
<u>MC</u>	Part Number	G700LTD
<u>PKG</u>	PKG Type	VDFN
	Pin/Ball Count	6
	PKG width/size	7x5x0.9mm

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Special Instructions
Standard Pb-free Solderability	J-STD-002D ; Perform 8 hours of steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	>95% lead coverage	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5		30 bonds from a min. 5 devices.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30		
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	
HTSL (High Temp Storage Life)	JESD22-A103 +125°C, +150°C or +175°C	45	5	1	50	0	Spares should be properly identified.
Preconditioning - Required for surface mount devices	J-STD-020JESD22-A113+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type MSL-1@260C	231+ 45 (for devices requiring PTC)	15+ 5 (for devices requiring PTC)	3	738+ 50 (for devices requiring PTC)	0	Spares should be properly identified.
HAST	JESD22-A101 or A110 +130°C/85% RH for 96 hrs or	77	5	3	246	0	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A102, A118, or A101 +130°C/85% RH for 96 hrs	77	5	3	246	0	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104 and Appendix 3 -65°C to +150°C	77	5	3	246	0	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.

CCB 4610
Pre and Post Change Summary
PCN#:KSRA-06MRSR308



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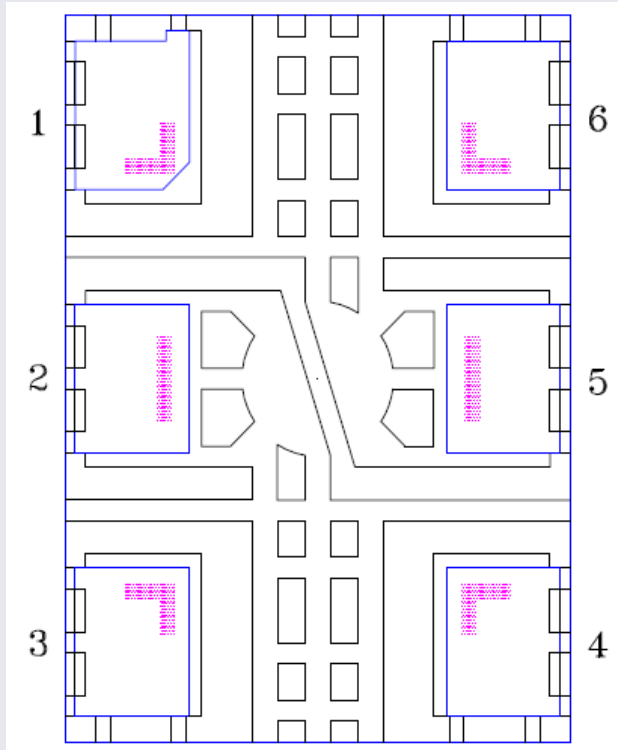


SMART | CONNECTED | SECURE

Lead frame comparison

Pre change

NSEB

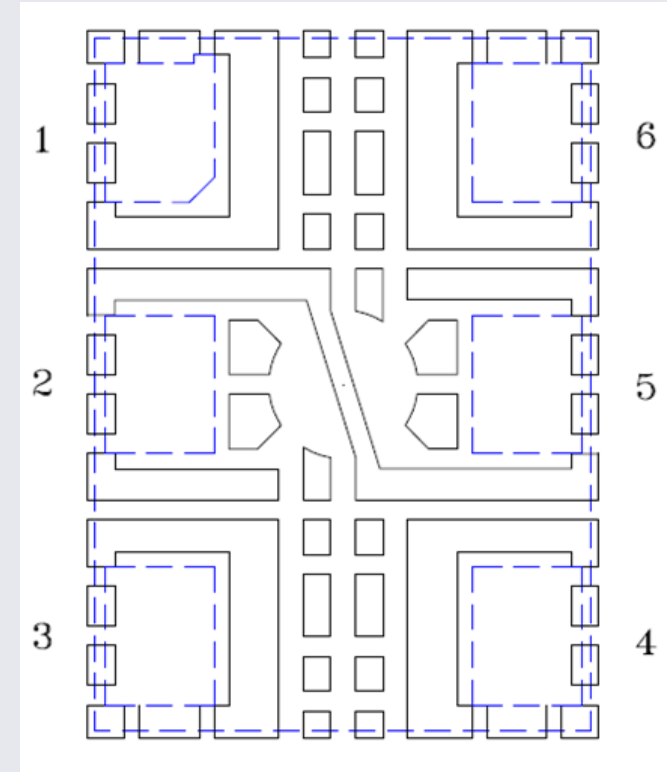


Lead frame DAP surface Prep

Selective PPF

Post Change

NSEB



Lead frame DAP surface Prep

Full PPF

Affected Catalog Part Numbers (CPN)

DSC1203NI2-148M5000
DSC1221NA1-27M00000
DSC1201NA3-PROG
DSC1203NA1-20M00000
DSC1211NA3-C0024
DSC1201NI2-129M6000
DSC1203NI1-100M0000
DSC1222NI2-156M2500
DSC1222NI2-150M0000
DSC1221NI2-125M0000
DSC1211NI3-C0018
DSC1224NI3-156M2500
DSC1213NI2-C0019
DSC1203NI2-148M3500
DSC1223NI1-100M0000
DSC1223NI1-135M0000
DSC1223NI1-106M2500
DSC1223NI1-148M5000
DSC1223NI2-200.0000
DSC1223NI1-125M0000
DSC1223NI1-156M0000
DSC1223NI1-156M2500
DSC1203NI3-148M3500
DSC1222NI1-50M00000
DSC1200NL3-PROG
DSC1202NE2-156M2600
DSC1204NL3-122M8800
DSC1204NL3-100M0000
DSC1221NE1-75M00000
DSC1204NL1-100M0000
DSC1201NE3-64M98000
DSC1202NE2-156M2617
DSC1201NE3-64M08000
DSC1211NE3-C0021
DSC1201NE3-24M57600
DSC1201NE3-20M97152
DSC1221NE3-48M00000
DSC1203NE1-125M0000
DSC1223NE1-125M0000
DSC1221NL1-125M0000
DSC1201NE1-2M500000
DSC1202NE3-75M00000
DSC1222NL3-10M00000
DSC1203NE3-15M00000
DSC1223NE3-15M00000
DSC1203NE3-120M0000

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DSC1200NL3-PROGT

DSC1202NE2-156M2600T
DSC1204NL3-122M8800T
DSC1204NL3-100M0000T
DSC1221NE1-75M00000T
DSC1204NL1-100M0000T
DSC1201NE3-64M98000T
DSC1202NE2-156M2617T
DSC1201NE3-64M08000T
DSC1211NE3-C0021T
DSC1201NE3-24M57600T
DSC1201NE3-20M97152T
DSC1221NE3-48M00000T
DSC1203NE1-125M0000T
DSC1223NE1-125M0000T
DSC1221NL1-125M0000T
DSC1201NE1-2M500000T
DSC1202NE3-75M00000T
DSC1222NL3-10M00000T
DSC1203NE3-15M00000T
DSC1223NE3-15M00000T
DSC1203NE3-120M0000T
DSC1203NI2-148M5000T
DSC1201NI2-129M6000T
DSC1203NI1-100M0000T
DSC1222NI2-156M2500T
DSC1222NI2-150M0000T
DSC1221NI2-125M0000T
DSC1211NI3-C0018T
DSC1224NI3-156M2500T
DSC1213NI2-C0019T
DSC1203NI2-148M3500T
DSC1223NI1-100M0000T
DSC1223NI1-135M0000T
DSC1223NI1-106M2500T
DSC1223NI1-148M5000T
DSC1223NI2-200.0000T
DSC1223NI1-125M0000T
DSC1223NI1-156M0000T
DSC1223NI1-156M2500T
DSC1203NI3-148M3500T
DSC1222NI1-50M00000T
DSC1201NA3-PROGT
DSC1203NA1-20M00000T
DSC1211NA3-C0024T
DSC8121NI2
DSC8122NI2
DSC8123NI2
DSC8124NI2

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DSC1101NI1-125.0062

DSC1101NI1-156.2500

DSC1101NI5-100.0000

DSC1103NI2-400.0000

DSC1121NI2-018.4320

DSC1122NI2-150.0000

DSC1123NI1-100.0000

DSC1123NI1-125.0000

DSC1123NI2-125.0000

DSC1123NI2-150.0000

DSC1123NI2-312.5000

DSC1101NI5-025.0000

DSC8122NI5

DSC1101NI5-020.0000

DSC1101NI5-012.8000

DSC1101NI5-016.3840

DSC1124NI1-100.0000

DSC1124NI1-156.2500

DSC1104NI2-100.0000

DSC1122NI5-025.0020

DSC1122NI2-050.0000

DSC1103NI2-125.0000

DSC1121NI1-100.0000

DSC1121NI2-125.0000

DSC1121NI2-025.0000

DSC1101NI1-050.0000

DSC1102NI5-156.2500

DSC1123NI1-156.2500

DSC1122NI2-156.2500

DSC1103NI2-148.5000

DSC1103NI2-156.2500

DSC1101NI5-018.7500

DSC1122NI2-148.5000

DSC1123NI2-200.0000

DSC1123NI5-100.0000

DSC1123NI5-125.0000

DSC1123NI5-156.2500

DSC1123NI5-322.2656

DSC1101NI2-050.0000

DSC1103NI1-135.0000

DSC1122NI5-025.0007

DSC1123NI3-050.0015

DSC1103NI5-150.0000

DSC1123NI2-100.0000

DSC1122NI5-200.0000

DSC1102NI5-400.0000

DSC1102NI5-200.0000

DSC1101NI2-025.0000

DSC1101NI2-018.7500

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DSC1103NE1-125.0000
DSC1103NE1-125.0000
DSC1122NE1-025.0000
DSC1122NE2-156.2500
DSC1124NE1-100.0000
DSC1122NE1-133.3330
DSC1122NE1-150.0000
DSC1123NE2-156.2500
DSC1123NE2-125.0000
DSC1123NL2-100.0000
DSC1102NE1-148.5000
DSC1102NE1-125.0000
DSC1103NE1-114.2850
DSC1123NE1-100.0000
DSC1123NL5-125.0000
DSC1123NL5-100.0000
DSC1121NL1-025.0000
DSC1101NL3-PROG
DSC1101NL5-PROG
DSC1100NL3-PROG
DSC1100NL5-PROG
DSC1122NL2-025.0006
DSC1103NL2-147.4560
DSC1103NL2-098.3040
DSC1123NE1-200.0000
DSC1103NL5-125.0000
DSC1103NL2-100.0000
DSC1103NL2-106.2500
DSC1103NL2-135.0000
DSC1102NE3-075.0000
DSC1103NE2-148.5000
DSC1123NL1-148.5000
DSC1122NE1-025.0000T
DSC1122NE2-150.0000T
DSC1122NE2-156.2500T
DSC1124NE1-100.0000T
DSC1124NL2-100.0000T
DSC1122NE1-133.3330T
DSC1122NE1-150.0000T
DSC1123NE2-156.2500T
DSC1123NE2-125.0000T
DSC1123NL2-100.0000T
DSC1102NE1-148.5000T
DSC1102NE1-125.0000T
DSC1103NE1-114.2850T
DSC1123NE1-100.0000T
DSC1123NL5-125.0000T
DSC1123NL5-100.0000T
DSC1121NL1-025.0000T

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DSC1101NL3-PROGT
DSC1101NL5-PROGT
DSC1100NL3-PROGT
DSC1100NL5-PROGT
DSC1122NL2-025.0006T
DSC1103NL2-147.4560T
DSC1103NL2-098.3040T
DSC1123NE1-200.0000T
DSC1103NL5-125.0000T
DSC1103NL2-100.0000T
DSC1103NL2-106.2500T
DSC1103NL2-135.0000T
DSC1102NE3-075.0000T
DSC1103NE2-148.5000T
DSC1123NL1-148.5000T
DSC1122NI2-150.0000T
DSC1123NI1-100.0000T
DSC1123NI2-125.0000T
DSC1124NI1-100.0000T
DSC1124NI1-156.2500T
DSC1123NI2-312.5000T
DSC1101NI5-025.0000T
DSC1101NI5-020.0000T
DSC1101NI5-012.8000T
DSC1101NI5-016.3840T
DSC1104NI2-100.0000T
DSC1122NI5-025.0020T
DSC1122NI2-050.0000T
DSC1103NI2-125.0000T
DSC1121NI1-100.0000T
DSC1121NI2-125.0000T
DSC1121NI2-025.0000T
DSC1101NI1-050.0000T
DSC1102NI5-156.2500T
DSC1123NI1-156.2500T
DSC1122NI2-156.2500T
DSC1103NI2-148.5000T
DSC1103NI2-156.2500T
DSC1101NI5-018.7500T
DSC1122NI2-148.5000T
DSC1123NI2-200.0000T
DSC1123NI5-100.0000T
DSC1123NI5-125.0000T
DSC1123NI5-156.2500T
DSC1123NI5-322.2656T
DSC1101NI2-050.0000T
DSC1103NI1-135.0000T
DSC1122NI5-025.0007T
DSC1123NI3-050.0015T

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DSC1103NI5-150.0000T
DSC1123NI2-100.0000T
DSC1122NI5-200.0000T
DSC1102NI5-400.0000T
DSC1102NI5-200.0000T
DSC1101NI2-025.0000T
DSC1101NI2-018.7500T
DSC1103NI5-300.0000T